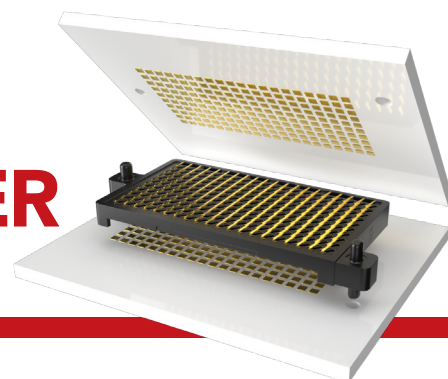


# SUPERNOVA® LOW PROFILE COMPRESSION INTERPOSER

PAM4

56  
G b p s



(1.00 mm) .0394" PITCH • GMI SERIES

## SPECIFICATIONS

### Insulator Material:

Black LCP

### Contact Material:

Copper Alloy

### Plating:

Au or 50 μ" (1.27 μm) Ni

### Current Rating:

.9 A per pin

(10 pins powered)

### Voltage Rating:

200 VAC/283 VDC

## PROCESSING

### Lead-Free Solderable:

Yes

### SMT Lead Complanarity:

(0.05 mm) .002" (10-20)\*

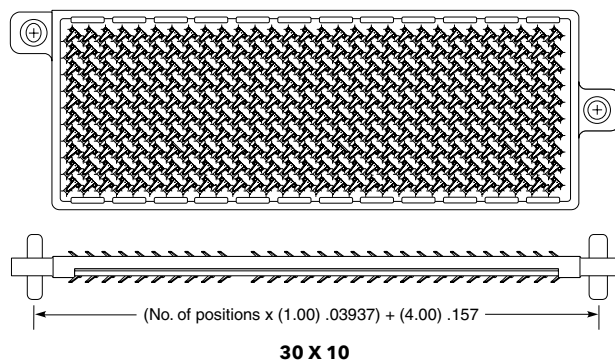
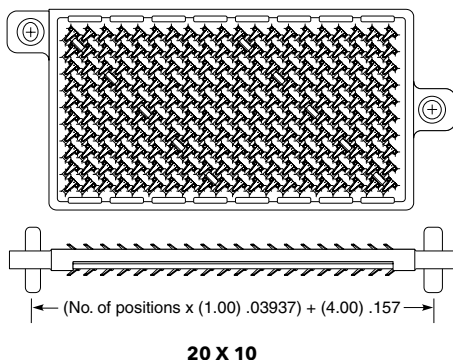
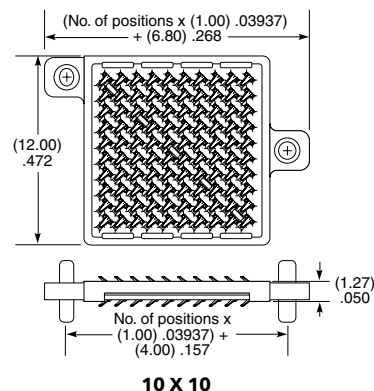
(0.08 mm) .003" (30)\*

\*(.004" stencil solution

may be available;

contact ipg@samtec.com)

| GMI | POSITIONS<br>PER ROW | STYLE                       | BOARD<br>SPACING                          | PLATING<br>OPTION                                     | ROWS              |
|-----|----------------------|-----------------------------|-------------------------------------------|-------------------------------------------------------|-------------------|
|     | -10, -20, -30        | -2<br>= Dual<br>Compression | -1.27<br>= (1.27 mm) .050"<br>Board Space | -G<br>= 10 μ"<br>(0.25 μm)<br>Gold on<br>contact area | -10<br>= Ten Rows |



### Note:

Some lengths, styles and options are non-standard, non-returnable